

## 微小チップ抵抗器電極上への無電解めっきの選択析出

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### Selective Electroless Deposition on Electrodes of Resistive Micro Chip Components

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#### Abstract

When a passive component electrode is metalized, conventional barrel electrolytic plating is used. However, as the size of the component becomes smaller, it is difficult to perform plating uniformly. In order to solve this problem, we carried out electroless plating, achieving selective electroless deposition on the metallic electrodes of the micro passive chip component.

**Key Words:** *Electroless Plating, High Density Packaging, Passive Chip Component*